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PRINTED CIRCUIT BOARD****Publication Classification**(71) Applicant: **SAMSUNG ELECTRONICS CO.,  
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**ABSTRACT**

An electronic device includes a microphone module and a printed circuit board on which the microphone module is disposed. The printed circuit board includes a first layer having at least one first microphone pad coupled to the microphone module, a first ground spaced apart from the first microphone pad, and a second microphone pad coupled to the microphone module and connected to the first ground; and a second layer disposed under the first layer and having a second ground opposite to the first microphone pad and at least a part of the first ground.

